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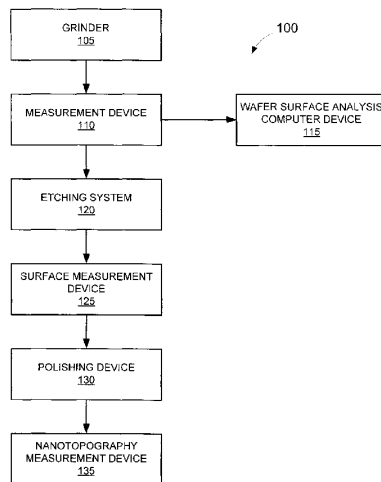
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(54) Title: SYSTEMS AND METHODS FOR ENHANCED WAFER MANUFACTURING



(57) Abstract: A computer device is provided. The computer device includes at least one processor in communication with at least one memory device. The at least one processor is programmed to store, in the at least one memory device, a model for simulating a portion of an assembly line and receive scan data of a first inspection of a product being assembled, execute the model using the scan data as inputs to generate a final profile of the product, compare the final profile to one or more thresholds, determine if the final profile exceeds at least one of the one or more thresholds, and adjust the first device if the determination is that the final profile exceeds at least one of the one or more thresholds.

FIG. 1

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